

Title (en)

COOLING DEVICE FOR COOLING COMPONENTS OF THE POWER ELECTRONICS, SAID DEVICE COMPRISING A MICRO HEAT EXCHANGER

Title (de)

KÜHLVORRICHTUNG ZUR KÜHLUNG VON BAUELEMENTEN DER LEISTUNGSELEKTRONIK MIT EINEM MIKROWÄRMEÜBERTRAGER

Title (fr)

DISPOSITIF DE REFROIDISSEMENT PERMETTANT DE REFROIDIR DES COMPOSANTS APPARTENANT AU DOMAINE DE L'ELECTRONIQUE DE PUISSANCE AU MOYEN D'UN MICROECHANGEUR THERMIQUE

Publication

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Application

EP 01913609 A 20010209

Priority

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- DE 10017971 A 20000411

Abstract (en)

[origin: WO0178478A1] The invention relates to a cooling device, especially for cooling components of the power electronics by means of a refrigerant which flows through a micro heat exchanger (10) that is provided with good heat contact to the component (1). The invention is characterised in that the refrigerant is selected in such a way that said refrigerant evaporates when the desired temperature in the micro heat exchanger (10) has been reached, whereby said temperature pertains to the component.

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H05K 7/20

IPC 8 full level

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